


## Full Material Declaration for attached parts list

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|  | <p><b>Diotec Semiconductor AG</b><br/> DUNS number: 330866844<br/> -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany<br/> Declarations authorised by:<br/> Udo Steinebrunner, Product Manager, -</p> |
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Declaration effective from: 01 January 2016 [Approved on 05 September 2025, 12:02 GMT]

## Materials and substances

| Use/Location  | Material Group            | % w/w of material in the part | Substances in the material   | CAS Number | % w/w of substance in the material |
|---------------|---------------------------|-------------------------------|--|------------|------------------------------------|
| Chip (die)    | Other inorganic materials | 1.9%                          | <b>Nickel</b><br>REACH Article 67 Exemption  | 7440-02-0  | 1%                                 |
|               |                           |                               | Gold   | 7440-57-5  | 11.5%                              |
|               |                           |                               | Silicon oxide  | 11126-22-0 | 25%                                |
|               |                           |                               | Silicon  | 7440-21-3  | 62.5%                              |
| Die attach    | Lead and Lead alloys      | 0.4%                          | Silver   | 7440-22-4  | 2.5%                               |
|               |                           |                               | Tin  | 7440-31-5  | 5%                                 |
|               |                           |                               | <b>Lead</b><br>EU RoHS Exemption 7(a)<br>Exempt from other regulatory requirements<br>Exempt from other regulatory requirements  | 7439-92-1  | 92.5%                              |
| Encapsulation | EP (Epoxy resin)          | 51.4%                         | Carbon black   | 1333-86-4  | 0.3%                               |
|               |                           |                               | <b>ANTIMONY TRIOXIDE</b><br>Exempt from other regulatory requirements  | 1309-64-4  | 0.8%                               |
|               |                           |                               | <b>3,5,3',5'-TETRABROMOBISPHENOL A</b><br>Exempt from other regulatory requirements<br>Exempt from other regulatory requirements | 79-94-7    | 0.99%                              |
|               |                           |                               | Epoxy resin 89   | 26335-32-0 | 27.61%                             |
|               |                           |                               | Quartz sand  | 60676-86-0 | 70.3%                              |
| Leadfinish    | Tin plating               | 1.7%                          | Tin  | 7440-31-5  | 100%                               |

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|--------------|---|-------------------------------|----------------------------|------------|------------------------------------|
| Leadframe    | Copper (e.g. copper amounts in cable harnesses) | 44.6%                         | Copper                     | 7440-50-8  | 100%                               |

Attached parts list

| Part number     | Part name       | Part Mass | Part Mass UoM |
|-----------------|-----------------|-----------|---------------|
| DO-214AC/SMA-GP | DO-214AC/SMA-GP | 0.07      | g             |

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